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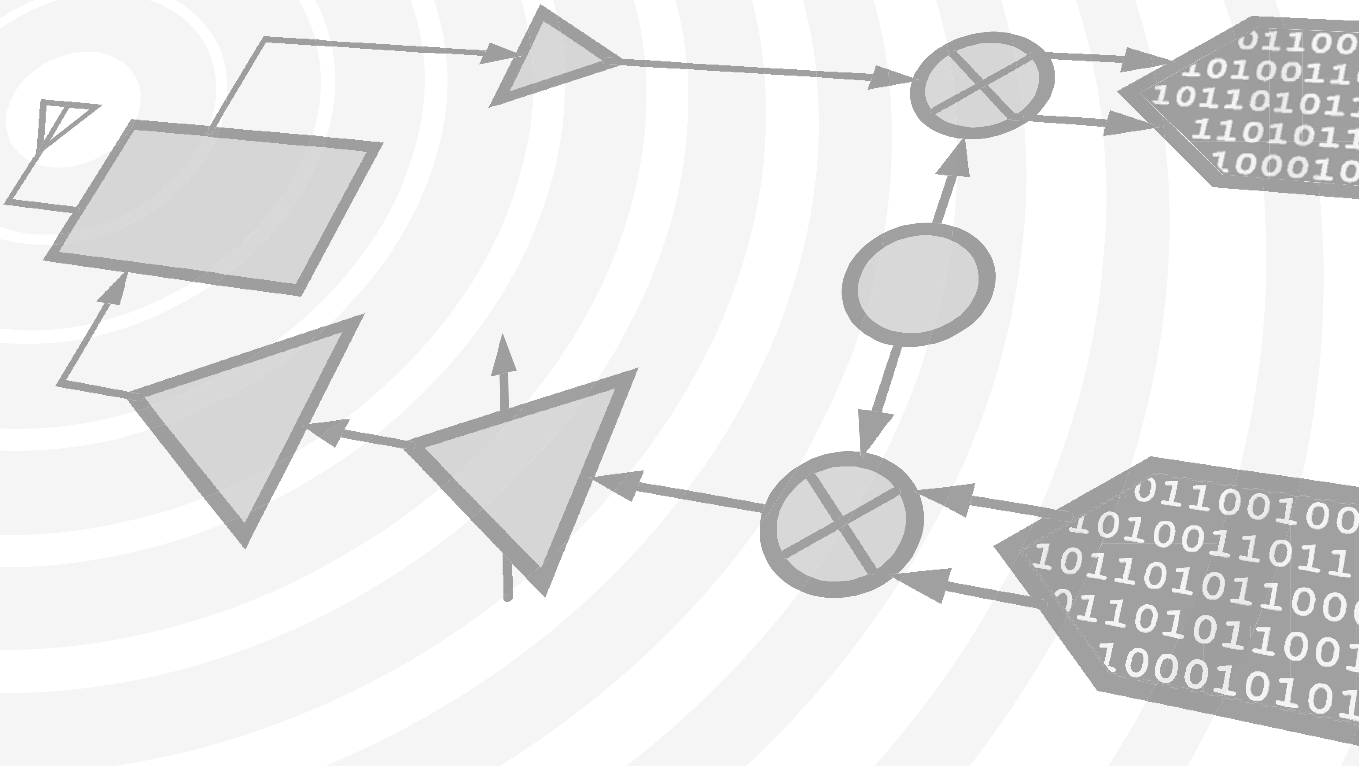
DEVICES

Hittite
MICROWAVE PRODUCTS
FROM ANALOG DEVICES

Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED



www.analog.com

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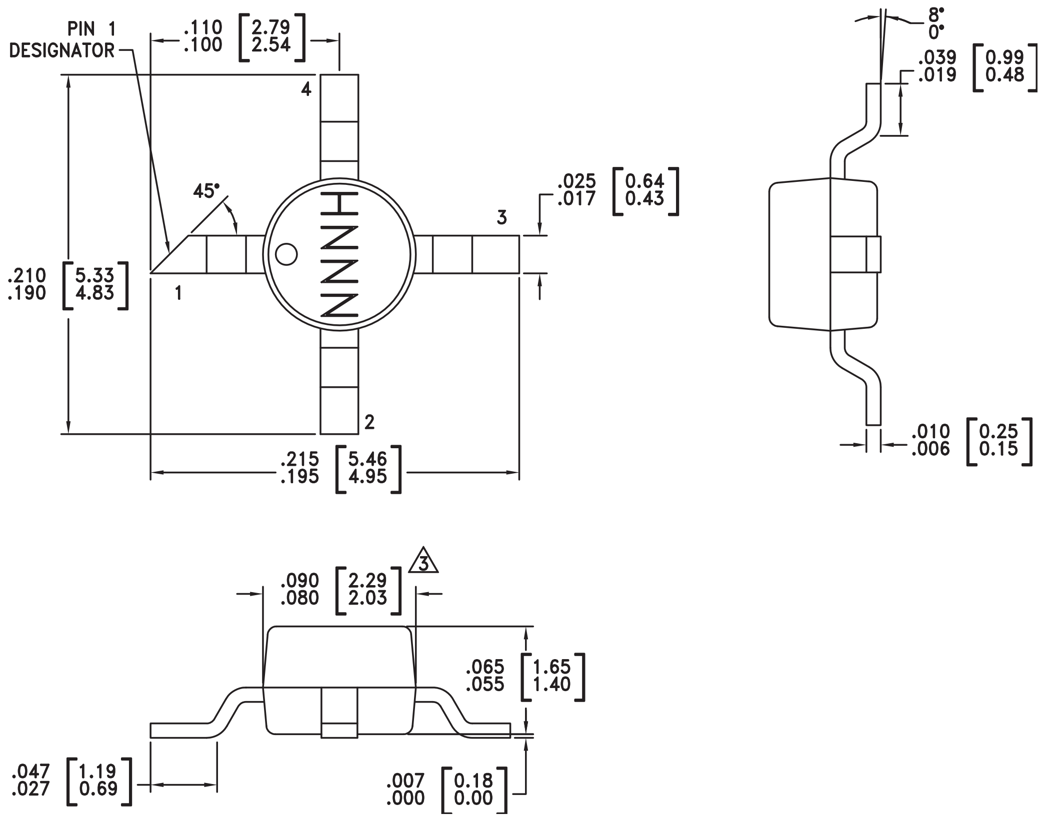
MP86 (E) – 4 LEAD PLASTIC MICRO-P PLASTIC PACKAGE (A.K.A. MICRO-X)

MP86 (E) Package Outline Drawing



NOTES:

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
5. THE MICRO-P PACKAGE IS DIMENSIONALLY COMPATIBLE WITH THE “MICRO-X PACKAGE”

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
MP86	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HNNN
MP86E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HNNN

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 3-Digit part number NNN

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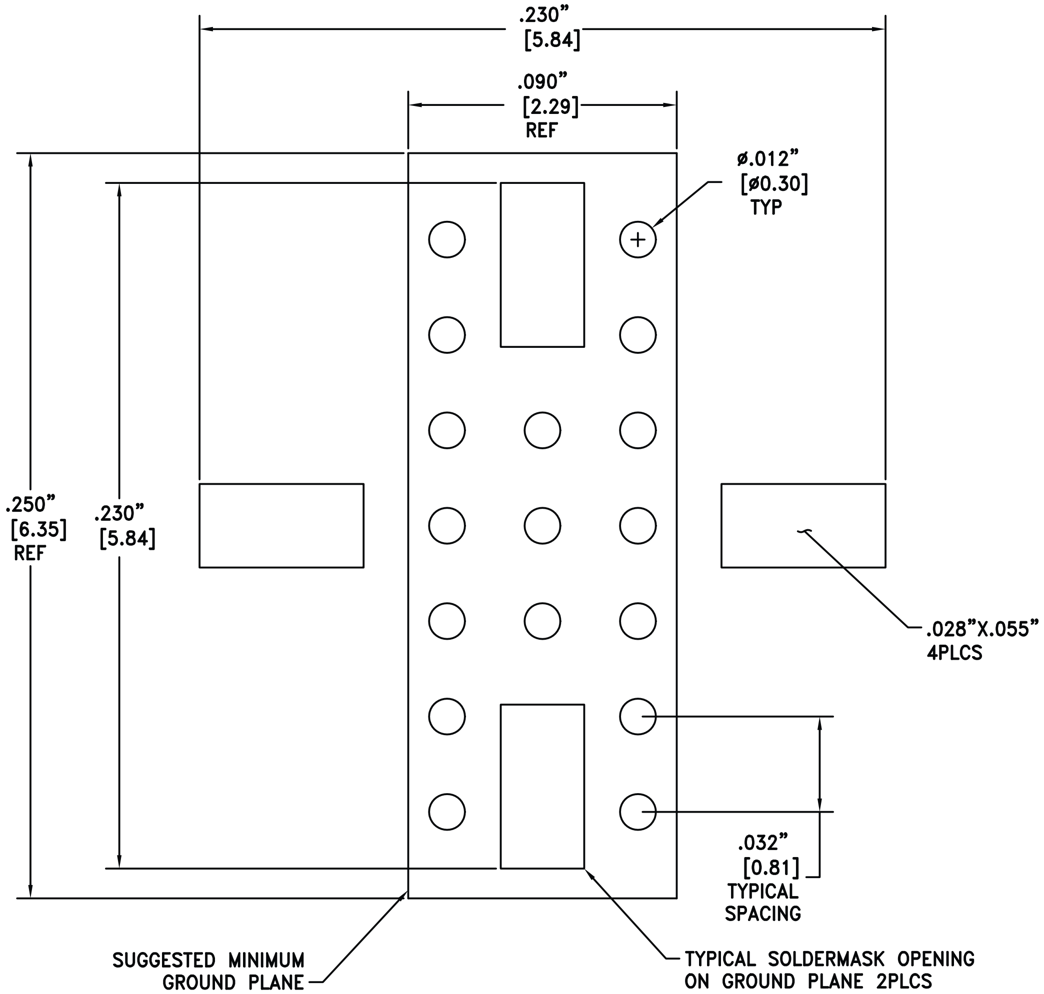
Suggested MP86 (E) PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.